



Title of Change:	Phase 2 Copper Wire for VHVIC Products in SOIC and TSSOP packages in Carmona, Philippines
Proposed first ship date:	28 September 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <Scott.Brow@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Ken.Fergus@onsemi.com>.
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Products affected on this FPCN will have part number date codes greater than WW16 2015.

Change category(s):

- | | | |
|---|---|---|
| <input type="checkbox"/> Wafer Fab Change | <input type="checkbox"/> Manufacturing Site Change/Addition | <input type="checkbox"/> Product specific change |
| <input checked="" type="checkbox"/> Assembly Change | <input type="checkbox"/> Manufacturing Process Change | <input type="checkbox"/> Datasheet/Product Doc change |
| <input type="checkbox"/> Test Change | <input checked="" type="checkbox"/> Material Change | <input type="checkbox"/> Shipping/Packaging/Marking |
| | | <input type="checkbox"/> Other: _____ |

Sites Affected:

- All site(s) not applicable
 ON Semiconductor site(s) :
 External Foundry/Subcon site(s):

Site 1
 ON Carmona, Philippines

Site 2

Description and Purpose:

The devices listed in this Notification were inadvertently omitted from the original FPCN16200. This FPCN can be pulled at www.onsemi.com under Quality Systems, Product Change Notifications. The date of conversion is set for September 28, 2015, and should provide adequate time for approval and sample requests to be fulfilled.

Reliability Data Summary:

Device NCP1236AD65R2G:

#	Test	Name	Test Conditions	End Point Req's	Test Results	(rej/ ss)	(rej/ ss)	(rej/ ss)	(rej/ ss)
					Read Point	Lot A	Lot B	Lot C	Lot 2 AU control lot
1	Prep	Sample preparation and initial part testing	Various	---	Initial Electrical	Done	Done	Done	Done
2	HTOL	High Temp Op Life	TA = 125°C biased	c = 0, Room, Hot	504 hours 1008 hours	0/77 0/77	0/77 0/77	0/77 0/77	0/77 0/77
3	PC	Preconditioning Test (Test@Rm) SMD only; Moisture preconditioning for HAST, UHAST, TC; Peak reflow Temp = 260C	MSL 1 260	Test at R		Done	Done	Done	Done
4	PC-HAST	Preconditioned Highly accelerated stress test	TA= +130°C, RH = 85%, PSIG= 18.8, bias	c = 0, Room, Hot	96 hours 192 hours	0/77 0/77	0/77 0/77	0/77 0/77	0/77 0/77
5	PC-UHAST	Preconditioned Highly accelerated stress test	TA= +130°C, RH = 85%, PSIG= 18.8	c = 0, Room, Hot	96 hours 192 hours	0/77 0/77	0/77 0/77	0/77 0/77	0/77 0/77
6	PC-TC	Preconditioned Temperature Cycle	-65/+150 C	c = 0, Room, Hot	500 cyc 1000cyc	0/77 0/77	0/77 0/77	0/77 0/77	0/77 0/77
6a	PC-TC DPA	Precond TC DPA AEC decap visual	-65/+150 C	C = 0	500 cyc	0/5	0/5	0/5	0/5
6b	WBP	Wire bond pull test: (Ppk >1.67 and Cpk >1.33)	Condition C at post 500 cycles	30 bonds coming from 5 units Cpk > 1.33	Post 500cycles TC	0/30	0/30	0/30	0/30
7	HTSL	High Temperature Storage Life	150C at 1008hrs	c = 0, Room, Hot	504 hours 1008 hours	0/77 0/77	0/77 0/77	0/77 0/77	0/77 0/77
8	RSH	Resistance to solder heat	JESD22 – B106 260°C Immersion	c = 0, Room, Hot	Pass	0/30	0/30	0/30	0/30



Device NCP1654BD65R2G:

#	Test	Name	Test Conditions	End Point Req's	Test Results	(rej/ ss)	(rej/ ss)	(rej/ ss)	(rej/ ss)
					Read Point	Lot A	Lot B	Lot C	Lot 2 AU control lot
1	Prep	Sample preparation and initial part testing	Various	---	Initial Electrical	Done	Done	Done	Done
2	HTOL	High Temp Op Life	TA = 125°C biased	c = 0, Room, Hot	504 hours	0/77	0/77	0/77	0/77
					1008 hours	0/77	0/77	0/77	0/77
3	PC	Preconditioning Test (Test@Rm) SMD only; Moisture preconditioning for HAST, UHAST, TC; Peak reflow Temp = 260C	MSL 1 260	Test at R		Done	Done	Done	Done
4	PC -HAST	Preconditioned Highly accelerated stress test	TA= +130°C, RH = 85%, PSIG= 18.8, bias	c = 0, Room, Hot	96 hours	0/77	0/77	0/77	0/77
					192 hours	0/77	0/77	0/77	0/77
5	PC -UHAST	Preconditioned Highly accelerated stress test	TA= +130°C, RH = 85%, PSIG= 18.8	c = 0, Room, Hot	96 hours	0/77	0/77	0/77	0/77
					192 hours	0/77	0/77	0/77	0/77
6	PC-TC	Preconditioned Temperature Cycle	-65/+150 C	c = 0, Room, Hot	500 cyc	0/77	0/77	0/77	0/77
					1000cyc	0/77	0/77	0/77	0/77
6a	PC-TC DPA	Precond TC DPA AEC decap visual	-65/+150 C	C = 0	500 cyc	0/5	0/5	0/5	0/5
6b	WBP	Wire bond pull test: (Ppk >1.67 and Cpk >1.33)	Condition C at post 500 cycles	30 bonds coming from 5 units Cpk > 1.33	Post 500cycles TC	0/30	0/30	0/30	0/30
7	HTSL	High Temperature Storage Life	150C at 1008hrs	c = 0, Room, Hot	504 hours	0/77	0/77	0/77	0/77
					1008 hours	0/77	0/77	0/77	0/77
8	RSH	Resistance to solder heat	JESD22 – B106 260°C Immersion	Test at R	Pass	0/30	0/30	0/30	0/30

Electrical Characteristic Summary:

There is no electrical characterization difference in products assembled with copper wire. Electrical data is available upon request.

List of Affected Standard Parts:

- NCP1606ADR2G
- NCP1606BDR2G
- NCP1562ADBR2G
- NCP1562BDBR2G